

5000W, 16V - 100V Surface Mount Transient Voltage Suppressor

FEATURES

- 5000W peak pulse power capability at 10/1000µs waveform
- Ideal for automated placement
- Photo glass passivated chip junction
- Excellent clamping capability
- Fast response time: Typically less than 1.0ps
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- I/O interface
- AC/DC power supply

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.300g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
V _{WM}	16 - 100	V		
V _{BR} (uni-directional)	17.8 - 123	٧		
P _{PPSM}	5000	W		
T _{J MAX}	175	°C		
Package	DO-214AB (SMC)			
Configuration	Stacked die			









DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Non-repetitive peak impulse power dissipation with 10/1000us waveform ⁽¹⁾	P _{PK}	5000	W	
Steady state power dissipation at $T_L = 75^{\circ}C^{(2)}$	P_{D}	6.25	W	
Forward Voltage @ I _F = 100A for Uni-directional only ⁽³⁾	V _F	5	V	
Junction temperature	T _J	-55 to +175	°C	
Storage temperature	T _{STG}	-55 to +175	°C	

Notes:

- 1. Non-repetitive current pulse per Fig.3 and derated above $T_A = 25$ °C per Fig.1
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)
- 3. Pulse test with PW = 0.3ms

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	R _{OJL}	16	°C/W	
Junction-to-ambient thermal resistance	R _{ÐJA}	61	°C/W	
Junction-to-case thermal resistance	R _{eJC}	17	°C/W	

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

Part number	Marking code	Break volta	age @l _⊤	Test current	Working stand- off	blocking leakage	Maximum peak impulse	Maximum clamping	Maximum Temp. coefficient
	Gode	(V (Not		I _T (mA)	voltage V _{WM}	current I _{IB} @V _{WM} (μΑ)	current	voltage V _C @I _{PP} (V)	of V _{BR} αV _{BR} @I _T
Uni	Uni	Min	Max		(V)	(Note 1)	(A)	(-)	(mV/°C)
5.0SMDJ16A	5PET	17.8	19.7	1	16	50	193	26.0	0.096
5.0SMDJ17A	5PEU	18.9	20.9	1	17	20	181	27.6	0.097
5.0SMDJ18A	5PEV	20.0	22.1	1	18	10	172	29.2	0.098
5.0SMDJ20A	5PEW	22.2	24.5	1	20	5	155	32.4	0.099
5.0SMDJ22A	5PEX	24.4	26.9	1	22	5	141	35.5	0.100
5.0SMDJ24A	5PEZ	26.7	29.5	1	24	2	129	38.9	0.101
5.0SMDJ26A	5PFE	28.9	31.9	1	26	2	119	42.1	0.101
5.0SMDJ28A	5PFG	31.1	34.4	1	28	2	110	45.4	0.102
5.0SMDJ30A	5PFK	33.3	36.8	1	30	2	103	48.4	0.103
5.0SMDJ33A	5PFM	36.7	40.6	1	33	2	93.9	53.3	0.104
5.0SMDJ36A	5PFP	40.0	44.2	1	36	2	86.1	58.1	0.104
5.0SMDJ40A	5PFR	44.4	49.1	1	40	2	77.6	64.5	0.105
5.0SMDJ43A	5PFT	47.8	52.8	1	43	2	72.1	69.4	0.105
5.0SMDJ45A	5PFV	50.0	55.3	1	45	2	68.8	72.7	0.106
5.0SMDJ48A	5PFX	53.3	58.9	1	48	2	64.7	77.4	0.106
5.0SMDJ51A	5PFZ	56.7	62.7	1	51	2	60.7	82.4	0.107
5.0SMDJ54A	5PGE	60.0	66.3	1	54	2	57.5	87.1	0.107
5.0SMDJ58A	5PGG	64.4	71.2	1	58	2	53.5	93.6	0.107
5.0SMDJ60A	5PGK	66.7	73.7	1	60	2	51.7	96.8	0.108
5.0SMDJ64A	5PGM	71.1	78.6	1	64	2	48.6	103	0.108
5.0SMDJ70A	5PGP	77.8	86.0	1	70	2	44.3	113	0.108
5.0SMDJ75A	5PGR	83.3	92.1	1	75	2	41.4	121	0.108
5.0SMDJ78A	5PGT	86.7	95.8	1	78	2	39.7	126	0.108
5.0SMDJ85A	5PGV	94.4	104	1	85	2	36.5	137	0.110
5.0SMDJ90A	5PGX	100	111	1	90	2	34.3	146	0.110
5.0SMDJ100A	5PGZ	111	123	1	100	2	30.9	162	0.110

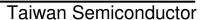
Note:

1. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾ PACKAGE PACKING			
5.0SMDJx	DO-214AB (SMC)	3,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 16V(5.0SMDJ16A) to 100V(5.0SMDJ100A)





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Pulse Power or Current vs. Initial Junction
Temperature

DENTING IN DESCRIPTION OF COURT OF COUR

Fig.2 Power Derating Curve

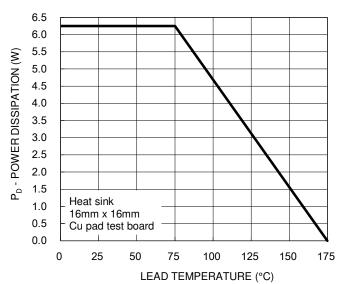


Fig.3 Pulse Waveform

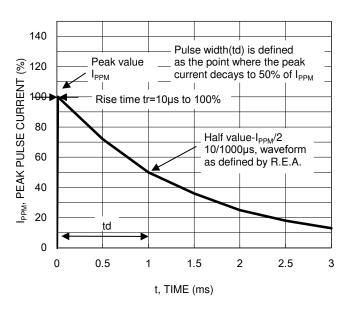
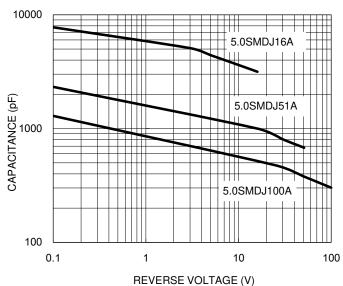


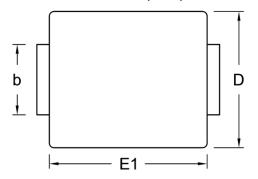
Fig.4 Typical Junction Capacitance

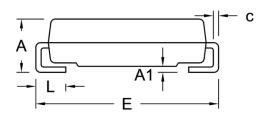




PACKAGE OUTLINE DIMENSIONS

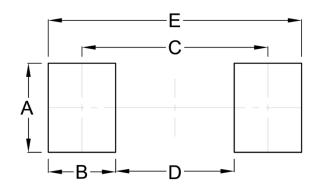
DO-214AB (SMC)





DIM.	Unit (mm)		Unit ((inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	2.00	2.62	0.079	0.103
A1	0.10	0.20	0.004	0.008
b	2.90	3.20	0.114	0.126
С	0.15	0.31	0.006	0.012
D	5.59	6.22	0.220	0.245
E	7.75	8.13	0.305	0.320
E1	6.60	7.11	0.260	0.280
L	1.00	1.60	0.039	0.063

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

ΥW = Date Code F = Factory Code



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